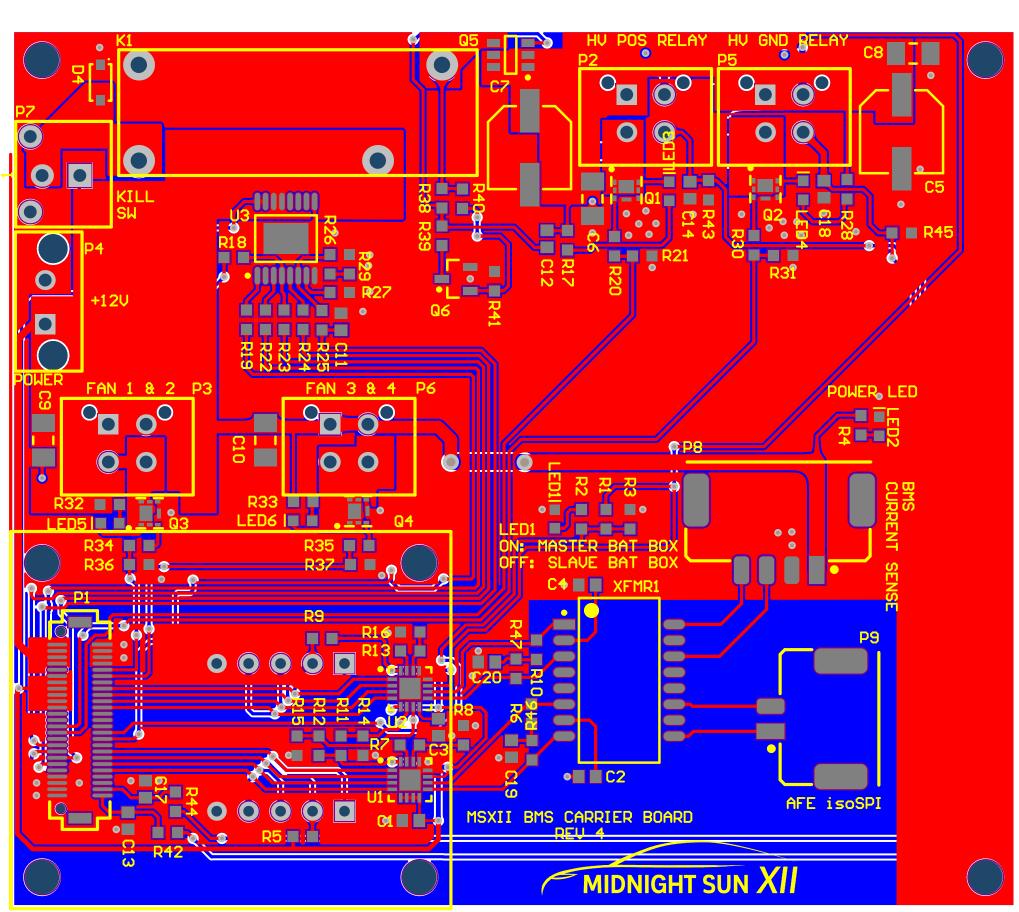
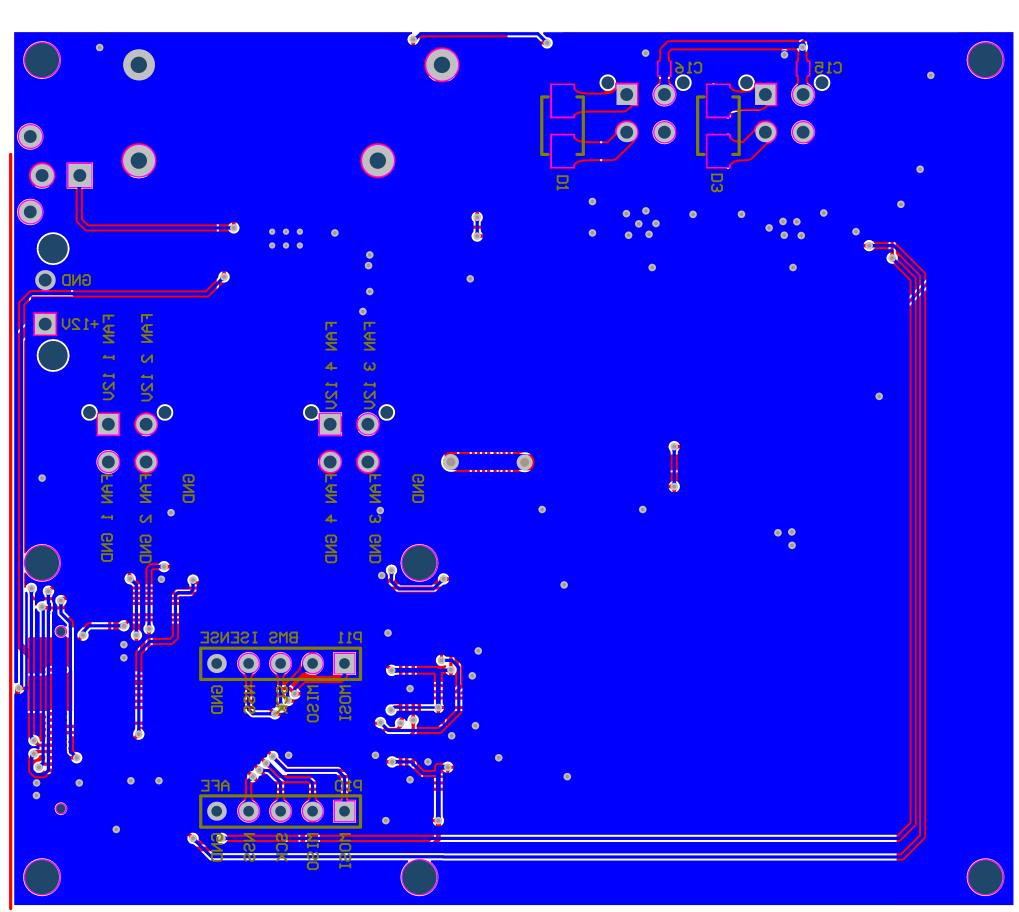


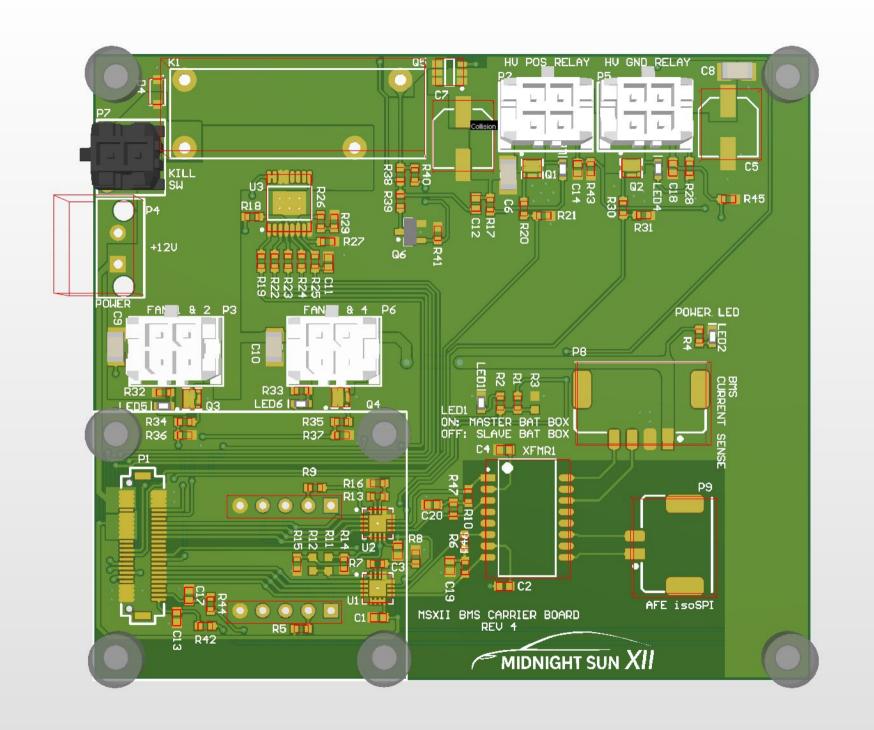
Bill of	Materials
Project:	BMS_Carrier_Board.PrjPcb
Revision:	<parameter found="" not="" projectrevision=""></parameter>
Project Lead:	Taiping Li
Generated On:	2019-03-26 8:57:15 PM
Production Quantity:	1
Currency	CAD
Total Parts Count:	95



LibRef CAP CER 0.1UF 50V 10% X7R 0603 CAP CER 20PF 50V ±5% C0G/NP0 0603	Designator	Manufacturer 1	Manufacturer Part Number 1	Supplier 1	Supplier Part Number 1	Supplier Unit Price 1	Committee Contra Charles		
								Supplier S	ubtotal 1
	C1	Kyocera AVX	06035C-104KAT2A	Digi-Key	478-5052-1-ND	0.21	1	s	0.21
	C2	Murata	GRM1885C1H200JA01D	Digi-Key	490-1410-1-ND	0.13	1	\$	0.13
CAP CER 0.1UF 50V 10% X7R 0603	C3	Kvocera AVX	06035C-104KAT2A	Digi-Key	478-5052-1-ND	0.21	1	\$	0.21
CAP CER 20PF 50V ±5% C0G/NP0 0603	C4	Murata	GRM1885C1H200JA01D	Digi-Key	490-1410-1-ND	0.13	1	\$	0.13
CAP ALUM 47UF 20% 35V SMD	C5	Panasonic	EEE1VA470WP	Digi-Key	PCE3961CT-ND	0.55	1	\$	0.55
CAP CER 2.2UF 100V ±20% X7R 1206	C6	Murata	GRM31CR72A225MA73L	Digi-Key	490-12773-1-ND				
CAP ALUM 47UF 20% 35V SMD	C7	Panasonic	EEE1VA470WP	Digi-Key	PCE3961CT-ND	0.55	1	\$	0.55
CAP CER 2.2UF 100V ±20% X7R 1206	C8	<u>Murata</u>	GRM31CR72A225MA73L	Digi-Key	490-12773-1-ND				
CAP CER 2.2UF 100V ±20% X7R 1206	C9	Murata	GRM31CR72A225MA73L	Digi-Key	490-12773-1-ND				
CAP CER 2.2UF 100V ±20% X7R 1206	C10	Murata	GRM31CR72A225MA73L	Digi-Key	490-12773-1-ND			-	
CAP CER 0.1UF 50V 10% X7R 0603	C11	Kyocera AVX	06035C-104KAT2A GRM188R61E475KE11D	Digi-Key	478-5052-1-ND	0.21	1	\$	0.21
CAP CER 4.7UF 25V 10% X5R 0603	C12	Murata		Digi-Key	490-7203-1-ND	0.49	1	\$	0.49
CAP CER 0.1UF 50V 10% X7R 0603	C13	Kyocera AVX KEMET	06035C-104KAT2A C0603C103J5JACTU	Digi-Key	478-5052-1-ND	0.21	1	-	0.21
CAP CER 10nF 50V 5% X7R 0603	C14	KEMET		Digi-Key	399-13384-1-ND	0.48		\$	0.48
CAP CER 10nF 50V 5% X7R 0603	C15	KEMET	C0603C103J5JACTU	Digi-Key	399-13384-1-ND	0.48	1	\$	0.48
CAP CER 10nF 50V 5% X7R 0603 CAP CER 0.1UF 50V 10% X7R 0603	C16 C17	KEME I Kvocera AVX	C0603C103J5JACTU 06035C-104KAT2A	Digi-Key	399-13384-1-ND 478-5052-1-ND	0.48 0.21	1	S	0.48
CAP CER 0.10F 50V 10% X7R 0603 CAP CER 10nF 50V 5% X7R 0603	C17	KFMFT	C0603C103J5JACTU	Digi-Key	399-13384-1-ND	0.21	1	S	0.48
CAP CER 10nF 50V 5% X7R 0603 CAP CER 10nF 50V 5% X7R 0603	C19	KEMET	C0603C103J5JACTU	Digi-Key Digi-Key	399-13384-1-ND	0.48	+		0.48
CAP CER 101F 50V 5% X/R 0603	C20	KEMET	C0603C103J5JACTU	Digi-Key Digi-Key	399-13384-1-ND	0.48	1	S	0.48
DIODE SCHOTTKY 60V 3A SMA	D1	Diodes	B360A-13-F	Digi-Key	B360A-FDICT-ND	0.55	1	S	0.46
DIODE SCHOTTKY 60V 3A SMA	D3	Diodes	B360A-13-F	Digi-Key	B360A-FDICT-ND	0.55	1	Š	0.55
		Diodes			1N4148WQ-7-FDICT-			,	
DIODE GEN PURP 100V 300MA SOD123	D4	Diodes Zetex	1N4148WQ-7-F	Digi-Key	ND	0.29	1	\$	0.29
RELAY SPST 12V 8A OMRON	K1	Omron	G6RN-1ADC12	Digi-Key	72346-ND	5.44	1	S	5.44
LED RED CLEAR 2V 0603	LED1	Wurth Electronics	150060RS75000	Digi-Key	732-4978-1-ND	0.19	1	Š	0.19
LED GREEN CLEAR 2V 0603	LED2	Wurth Electronics	150060VS75000	Digi-Key	732-4980-1-ND	0.19	1	S	0.19
LED YELLOW CLEAR 2.1V 0603	LED3	Wurth Electronics	150060YS75000	Digi-Key	732-4981-1-ND	0.19	1	\$	0.19
LED YELLOW CLEAR 2.1V 0603	LED4	Wurth Electronics	150060YS75000	Digi-Key	732-4981-1-ND	0.19	1	\$	0.19
LED YELLOW CLEAR 2.1V 0603	LED5	Wurth Electronics	150060YS75000	Digi-Key	732-4981-1-ND	0.19	1	\$	0.19
LED YELLOW CLEAR 2.1V 0603	LED6	Wurth Electronics	150060YS75000	Digi-Key	732-4981-1-ND	0.19	1	\$	0.19
CONN 50POS Bergstak Plug 0.02*	P1	Amphenol FCI	10132797-055100LF	Digi-Key	609-5226-1-ND	1.87	1	\$	1.87
CONN 4POS MICROFIT (2x2)	P2	Molex	43045-0427	Digi-Key	WM10667-ND	1.79	1	\$	1.79
CONN 4POS MICROFIT (2x2)	P3	Molex	43045-0427	Digi-Key	WM10667-ND	1.79	1	\$	1.79
CONN 2POS ULTRA-FIT 0.138"	P4	Molex	1722861302	Digi-Key	WM11673-ND	1.95	1	\$	1.95
CONN 4POS MICROFIT (2x2)	P5	Molex	43045-0427	Digi-Key	WM10667-ND	1.79	1	\$	1.79
CONN 4POS MICROFIT (2x2)	P6	Molex	43045-0427	Digi-Key	WM10667-ND	1.79	1	\$	1.79
CONN 2POS MICRO-FIT 3mm	P7	Molex	0430450227	Digi-Key	WM10657-ND	1.12	1	\$	1.12
CONN 4POS DURA-CLIK 0.079"	P8	Molex	<u>560020-0420</u>	Digi-Key	WM10864CT-ND	2.22	1	\$	2.22
CONN 2POS DURA-CLIK 0.079" VERT	P9	Molex	560020-0220	Digi-Key	WM10862CT-ND	1.04	1	\$	1.04
CONN 5POS HEADR MALE 0.1"	P10	Molex	<u>22-28-4050</u>	Digi-Key	WM50014-05-ND	0.32	1	\$	0.32
CONN 5POS HEADR MALE 0.1"	P11	Molex	22-28-4050	Digi-Key	WM50014-05-ND	0.32	1	\$	0.32
MOSFET N-CH 30V 8.7A 2.1W 6-PQFN (2x2)	Q1	Infineon	IRLHS6342TRPBF	Digi-Key	IRLHS6342TRPBFCT-	0.9	1	s	0.90
MOOFETT OF GOVERNOUS AND THE CENTER		minoss	1132 1232 12 113 21	Digi Hoy	<u>ND</u>	0.0		ř.	0.00
MOSFET N-CH 30V 8.7A 2.1W 6-PQFN (2x2)	Q2	Infineon	IRLHS6342TRPBF	Digi-Key	IRLHS6342TRPBFCT-	0.9	1	\$	0.90
				99	<u>ND</u>	***		<u> </u>	
MOSFET N-CH 30V 8.7A 2.1W 6-PQFN (2x2)	Q3	Infineon	IRLHS6342TRPBF	Digi-Key	IRLHS6342TRPBFCT-	0.9	1	s	0.90
				99	<u>ND</u>	***	·	ř–	
MOSFET N-CH 30V 8.7A 2.1W 6-PQFN (2x2)	Q4	Infineon	IRLHS6342TRPBF	Digi-Key	IRLHS6342TRPBFCT-	0.9	1	\$	0.90
		· · · · · · · · · · · · · · · · · · ·			ND			i —	
MOSFET P-CH 30V 4A 1.6W SOT-23-6	Q5	STMicroelectronics	STT4P3LLH6	Digi-Key	497-15521-1-ND	0.87	1	\$	0.87
MOSFET N-CH 60V 310MA SOT23	Q6	Diodes	DMN65D8L-7	Digi-Key	DMN65D8L-7DICT-ND	0.25	1	\$	0.25
RES 0.0 OHM 1/4W 0603	R1	Vishay Dale	CRCW06030000Z0EAHP	Digi-Key	541-0.0SBCT-ND	0.23	1	\$	0.23
RES 604 OHM 1% 1/10W 0603	R2	Yageo	RC0603FR-07604RL	Digi-Key	311-604HRCT-ND	0.13	1	\$	0.13
RES 4.7K OHM 1% 1/10W 0603	R4	Yageo Phycomp	RC0603FR-074K7L	Digi-Key	311-4.70KHRCT-ND	0.13	1	\$	0.13
RES 2K OHM 1% 1/10W 0603	R5 R6	Yageo	RC0603FR-072KL ERA3AEB620V	Digi-Key	311-2.00KHRCT-ND P62DBCT-ND	0.13	1	\$	0.13
RES 62 OHM 0.1% 1/10W 0603 RES 1.4k OHM 1% 1/10W 0603	R6 R7	Panasonic Yaqeo	RC0603FR-071K4I	Digi-Key	311-1.40KHRCT-ND	0.47	1	\$	0.47
		Yageo		Digi-Key		0.13	1	\$	0.13
RES 604 OHM 1% 1/10W 0603 RES 2K OHM 1% 1/10W 0603	R8 R9	Yageo V	RC0603FR-07604RL RC0603FR-072KI	Digi-Key	311-604HRCT-ND 311-2 00KHRCT-ND	0.13 0.13		3	0.13
	R10	Panasonic	ERA3AEB620V	Digi-Key	P62DBCT-ND	0.13	1	3	
RES 62 OHM 0.1% 1/10W 0603 RES 1.4k OHM 1% 1/10W 0603	R13	Panasonic	RC0603FR-071K4L	Digi-Key Digi-Key	311-1.40KHRCT-ND	0.47	1	S	0.47
RES 0.0 OHM 1/4W 0603	R14	Vishay Dale	CRCW06030000Z0EAHP	Digi-Key Digi-Key	541-0.0SBCT-ND	0.13	1	S	0.13
RES 0.0 OHM 1/4W 0603	R15	Vishay Dale	CRCW06030000Z0EAHP	Digi-Key Digi-Key	541-0.0SBCT-ND	0.23	1	\$	0.23
RES 604 OHM 1% 1/10W 0603	R16	Voces	RC0603FR-07604RL	Digi-Key	311-604HRCT-ND	0.13		ě	0.13
RES 4.7K OHM 1% 1/10W 0603	R17	Yageo Phycomp	RC0603FR-074K7L	Digi-Key Digi-Key	311-4.70KHRCT-ND	0.13	1	S	0.13
RES 4.7K OHM 1% 1/10W 0603	R18	Yageo Phycomp	RC0603FR-074K7L	Digi-Key	311-4.70KHRCT-ND	0.13	1	\$	0.13
RES 4.7K OHM 1% 1/10W 0603	R19	Yageo Phycomp	RC0603FR-074K7L	Digi-Key Digi-Key	311-4.70KHRCT-ND	0.13	1	Š	0.13
RES 22.1 OHM 1% 1/10W 0603	R20	Yageo	RC0603FR-0722R1L	Digi-Key	311-22.1HRCT-ND	0.13	1	S	0.13
RES 10K OHM 1% 1/10W 0603	R21	Yageo Phycomp	RC0603FR-0710KL	Digi-Key	311-10.0KHRCT-ND	0.13	1	\$	0.13
RES 4.7K OHM 1% 1/10W 0603	R22	Yageo Phycomp	RC0603FR-074K7L	Digi-Key	311-4.70KHRCT-ND	0.13	1	\$	0.13
RES 4.7K OHM 1% 1/10W 0603	R23	Yageo Phycomp	RC0603FR-074K7L	Digi-Key	311-4.70KHRCT-ND	0.13	1	\$	0.13
RES 4.7K OHM 1% 1/10W 0603	R24	Yageo Phycomp	RC0603FR-074K7L	Digi-Key	311-4.70KHRCT-ND	0.13	1	\$	0.13
RES 4.7K OHM 1% 1/10W 0603	R25	Yageo Phycomp	RC0603FR-074K7L	Digi-Key	311-4.70KHRCT-ND	0.13	1	\$	0.13
RES 3.3K OHM 1% 1/4W 0603	R26	Panasonic	ERJPA3F3301V	Digi-Key	P3.3KBYCT-ND	0.21	1	\$	0.21
RES 4.7K OHM 1% 1/10W 0603	R27	Yageo Phycomp	RC0603FR-074K7L	Digi-Key	311-4.70KHRCT-ND	0.13	1	\$	0.13
RES 4.7K OHM 1% 1/10W 0603	R28	Yageo Phycomp	RC0603FR-074K7L	Digi-Key	311-4.70KHRCT-ND	0.13	1	\$	0.13
RES 2K OHM 1% 1/10W 0603	R29	Yageo	RC0603FR-072KL	Digi-Key	311-2.00KHRCT-ND	0.13	1	\$	0.13
RES 22.1 OHM 1% 1/10W 0603	R30	Yageo	RC0603FR-0722R1L	Digi-Key	311-22.1HRCT-ND	0.13	1	\$	0.13
RES 10K OHM 1% 1/10W 0603	R31	Yageo Phycomp	RC0603FR-0710KL	Digi-Key	311-10.0KHRCT-ND	0.13	1	\$	0.13
RES 4.7K OHM 1% 1/10W 0603	R32	Yageo Phycomp	RC0603FR-074K7L	Digi-Key	311-4.70KHRCT-ND	0.13	1	\$	0.13
RES 4.7K OHM 1% 1/10W 0603	R33	Yageo Phycomp	RC0603FR-074K7L	Digi-Key	311-4.70KHRCT-ND	0.13	1	2	0.13
RES 22.1 OHM 1% 1/10W 0603	R34	Yageo	RC0603FR-0722R1L	Digi-Key	311-22.1HRCT-ND	0.13	1	\$	0.13
RES 22.1 OHM 1% 1/10W 0603	R35	Yageo Vageo Physograp	RC0603FR-0722R1L	Digi-Key	311-22.1HRCT-ND	0.13	1	\$	0.13
RES 10K OHM 1% 1/10W 0603 RES 10K OHM 1% 1/10W 0603	R36 R37	Yageo Phycomp	RC0603FR-0710KL RC0603FR-0710KL	Digi-Key	311-10.0KHRCT-ND 311-10.0KHRCT-ND	0.13	1	\$	0.13
RES 10K OHM 1% 1/10W 0603 RES 330 OHM 1% 1/10W 0603	K3/	Yageo Phycomp	1-2176220 0	Digi-Key Digi-Key	A130693TD AID	0.13	1	-	0.13
RES 330 OHM 1% 1/10W 0603 RES 1K OHM 5% 1/10W 0603	R38 R39	TE Connectivity Yageo	1-2176339-9 RC0603JR-071KL	Digi-Key	A129682TR-ND 311-1.0KGRCT-ND	0.13	1	s	0.13
RES 1R OHW 5% 1/10W 0603 RES 0.0 OHM 1/4W 0603	R39 R40	Vishay Dale	CRCW06030R-071KL	Digi-Key Digi-Key	541-0.0SBCT-ND	0.13	1	S	0.13
RES 10K OHM 1% 1/10W 0603	R40	Yageo Phycomp	RC0603FR-0710KI		311-10.0KHRCT-ND	0.13	1	S	0.23
RES 10R OHM 1% 1/10W 0603 RES 1K OHM 5% 1/10W 0603	R41 R42	Yageo Phycomp Yageo	RC0603FR-0710KL	Digi-Key Digi-Key	311-10.0KHRC1-ND	0.13	1	ě	0.13
RES 10K OHM 5% 1/10W 0603 RES 10K OHM 1% 1/10W 0603	R42 R43	Yageo Phycomp	RC0603FR-071KL	Digi-Key Digi-Key	311-1.0KGRC1-ND	0.13	1	S	0.13
RES 1K OHM 5% 1/10W 0603	R43	Yageo Priycomp Yageo	RC0603FR-0710KL RC0603JR-071KI	Digi-Key Digi-Key	311-10.0KHRC1-ND	0.13	1	S	0.13
RES 10K OHM 1% 1/10W 0603	R45	Yageo Phycomp	RC0603FR-0710KL	Digi-Key Digi-Key	311-10.0KHRCT-ND	0.13	1	S	0.13
RES 62 OHM 0.1% 1/10W 0603	R45	Panasonic	ERA3AEB620V	Digi-Key Digi-Key	P62DBCT-ND	0.13	1	S	0.13
RES 62 OHM 0.1% 1/10W 0603	R47	Panasonic	ERA3AEB620V	Digi-Key Digi-Key	P62DBCT-ND	0.47	1	S	0.47
		Analog Devices / Linear	<u> LTO IOI IL DOLOV</u>					*	
IC ISOSPI COMM INTERFACE LTC6820IUD	U1	Technology	LTC6820IUD#PBF	Digi-Key	LTC6820IUD#PBF-ND	7.44	1	\$	7.44
	Lie	Analog Devices / Linear	I TOOODOU TO HORE	District	I TOOOOOU IS ISSUE !	7			
10.10.0001.00111.11.000	U2	Technology	LTC6820IUD#PBF	Digi-Key	LTC6820IUD#PBF-ND	7.44	1	\$	7.44
IC ISOSPI COMM INTERFACE LTC6820IUD	OL.								
			TDC2LI000DODWDDO:	Diel V	TPS2H000BQPWPRQ1-				
IC ISOSPI COMM INTERFACE LTC6820IUD IC HSD Dual-Channel 40V 1KOhm	U3	Texas Instruments	TPS2H000BQPWPRQ1	Digi-Key	ND				
IC HSD Dual-Channel 40V 1KOhm	U3	Texas Instruments			ND PT61018AAPEL-SCT-	5 12	4		E 10
			TPS2H000BQPWPRQ1 PT61018AAPEL-S	Digi-Key Digi-Key	ND	5.12	1 Total:	\$	5.12







Electrical Rules Check Report

Class	Document	Message
Warning	BMS Carrier - Firmware Contactor	Global Power-Object 3V3 at 2600mil,5100milhas been reduced to local level by presence of
	Control.SchDoc	port at 2800mil,4500mil
Warning	BMS Carrier - AFE Interface.SchDoc	incorrect link between project variant "BMS Carrier - Slave Battery Box" and schematic
		component Component R6 62R
Warning	Controller_Board_Interface.SchDoc	Net 3V3 has no driving source (Pin C1-1,Pin C3-1,Pin C15-1,Pin C16-1,Pin P1-40,Pin
		P1-41,Pin P1-42,Pin P1-43,Pin P1-44,Pin P1-45,Pin P2-3,Pin P5-3,Pin R1-1,Pin R5-1,Pin
		R9-1,Pin R11-1,Pin R12-1,Pin R18-2,Pin U1-5,Pin U1-6,Pin U1-7,Pin U1-8,Pin U1-11,Pin
Error	BMS Carrier - Connectors.SchDoc	U1-16 Pin U2-5 Pin U2-8 Pin U2-11 Pin U2-16) Net 12V_CONTACTOR_COIL_SW contains multiple Input Ports (Porl
2	2	12V CONTACTOR COIL SW,Port 12V CONTACTOR COIL SW)
Error	BMS Carrier - Battery Relay	Net 12V_CONTACTOR_COIL_SW contains multiple Input Ports (Port
	Controls.SchDoc	12V_CONTACTOR_COIL_SW,Port 12V_CONTACTOR_COIL_SW,Port
		HV GND RELAY 12V SW.Port HV PWR RELAY 12V SW)
Error	BMS Carrier - Battery Relay	Net 12V_CONTACTOR_CÓIL_SW contains multiple Input Ports (Porl
	Controls.SchDoc	HV GND RELAY 12V SW,Port HV PWR RELAY 12V SW)
Error	BMS Carrier - Battery Relay	Net NetD1_1 contains multiple Input Ports (Port HV_PWR_RELAY_GND,Port
	Controls.SchDoc	HV_PWR_RELAY_GND)
Error	BMS Carrier - Battery Relay	Net NetD3_1 contains multiple Input Ports (Port HV_GND_RELAY_GND,Porl
	Controls.SchDoc	HV_GND_RELAY_GND)
Error	BMS Carrier - Fan Controls.SchDoc	Net NetLED5_2 contains multiple Input Ports (Port FAN_1_GND,Port FAN_1_GND)
Error	BMS Carrier - Fan Controls.SchDoc	Net NetLED6_2 contains multiple Input Ports (Port FAN_2_GND,Port FAN_2_GND)
Error	BMS Carrier - Fan Controls.SchDoc	Net PA9_FAN_2_PWM contains multiple Input Ports (Port PA9_FAN_2_PWM,Port
		PA9_FAN_2_PWM)
Error	BMS Carrier - Fan Controls.SchDoc	Net PA10_FAN_1_PWM contains multiple Input Ports (Port PA10_FAN_1_PWM,Porl
		PA10_FAN_1_PWM)
Warning	Controller_Board_Interface.SchDoc	Net PB0_MOSFET_SOFT_START_INPUT has no driving source (Pin P1-17)
Error	BMS Carrier - AFE Interface.SchDoc	Net PB0_MOSFET_SOFT_START_INPUT has only one pin (Pin P1-17)
Warning	BMS Carrier - Battery Relay	Unconnected line (4850mil,2100mil) To (4950mil,2100mil)
	Controls.SchDoc	
	·	

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Design Rules Verification ReportFilename : C:\Users\Aashmika Mali\Documents\First Year\Midnight Sun\hardware\MSXII_BN

Warnings 0 Rule Violations 99

Warnings Total 0

Rule Violations	
Clearance Constraint (Gap=0.152mm) (All),(All)	0
Short-Circuit Constraint (Allowed=No) (All),(All)	0
Un-Routed Net Constraint ((All))	0
Modified Polygon (Allow modified: No), (Allow shelved: No)	0
Width Constraint (Min=0.203mm) (Max=2.54mm) (Preferred=0.203mm) (All)	0
Power Plane Connect Rule(Direct Connect) (Expansion=0.508mm) (Conductor Width=0.254mm) (Air Gap=0.254mm)	0
Hole Size Constraint (Min=0.025mm) (Max=5.08mm) (All)	0
Hole To Hole Clearance (Gap=0.254mm) (All),(All)	0
Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)	99
Silk To Solder Mask (Clearance=0.254mm) (Disabled)(IsPad),(All)	0
Silk to Silk (Clearance=0.254mm) (Disabled)(All),(All)	0
Net Antennae (Tolerance=0mm) (All)	0
Height Constraint (Min=0mm) (Max=25.4mm) (Prefered=12.7mm) (All)	0
Total	99

Page 1 of 3

Minimum Colder Mock Cliver (Con. 0.25 Amm) (All) (All)
Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All) Minimum Solder Mask Sliver Constraint: (0.244mm < 0.254mm) Between Pad C13-1(9.324mm,7.675mm) on Top Layer And Pad
Minimum Solder Wask Silver Constraint: (0.244mm < 0.254mm) Between Pad C15-1(7.324mm) on Multi-Layer And Pad P1-(5.5mm,22.8mm) on Top
Minimum Solder Mask Sliver Constraint: (0.105mm < 0.254mm) Between Pad P1-(4mm,7.95mm) on Multi-Layer And Pad P1-(5.5mm,7.2mm) on Top
Millimum Solder Mask Sliver Constraint: (0.105/mm < 0.254mm) Between Pad P1-(4/mm,7.59mm) on Widit-Layer And Pad P1-(5.5mm,7.2mm) on Top Layer And Pad
Minitiating States Was 1879 Mer Constraint: (0.047mm < 0.254mm) Between Pad Q1-2(48.025mm,57.15mm) on Top Layer And Pad
Minif(46h085irder), Maskrishi) er Constraint: (0.047mm < 0.254mm) Between Pad Q1-3(48.025mm, 56.5mm) on Top Layer And Pad
Minif(48h9Solde FM4Skn9Sh)ver Constraint: (0.202mm < 0.254mm) Between Pad Q1-3(48.025mm,56.5mm) on Top Layer And Pad
MinB(48h9Solde,5Maishr8hi), er Constraint: (0.047mm < 0.254mm) Between Pad Q1-4(49.875mm,56.5mm) on Top Layer And Pad
Qinbi(4) 85 Inder Was 50 Mover Constraint: (0.047mm < 0.254mm) Between Pad Q1-4(49.875mm, 56.5mm) on Top Layer And Pad
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MinB(48h9Solde,5Maskn9sh)ver Constraint: (0.047mm < 0.254mm) Between Pad Q1-5(49.875mm,57.15mm) on Top Layer And Pad
Minio (49/1885) tder, Masking Ni)ver Constraint: (0.187mm < 0.254mm) Between Pad Q1-7(48.95mm, 57.45mm) on Top Layer And Pad
Minandam Storing Constraint: (0.047mm < 0.254mm) Between Pad Q2-1(59.075mm,57.884mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q2-2(59.075mm,57.234mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q2-3(59.075mm,56.584mm) on Top Layer And Pad
ManifoomBotile Filter Maskr Sliver Constraint: (0.202mm < 0.254mm) Between Pad Q2-3(59.075mm,56.584mm) on Top Layer And Pad
Manacomsolute A Maskristiver Constraint: (0.047mm < 0.254mm) Between Pad Q2-4(60.925mm,56.584mm) on Top Layer And Pac
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Manage Agriculture Constraint: (0.047mm < 0.254mm) Between Pad Q2-5(60.925mm,57.234mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.187mm < 0.254mm) Between Pad Q2-7(60mm,57.534mm) on Top Layer And Pad Q2-8(60mm,56.494mm)
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q3-1(10.4mm,30.525mm) on Top Layer And Pad
ΩներՁին Մեր β Masa և Simpler Constraint: (0.047mm < 0.254mm) Between Pad Q3-2(11.05mm,30.525mm) on Top Layer And Pad
Mahara (ប្រាក្ស Sort) a Skn Shi)ver Constraint: (0.047mm < 0.254mm) Between Pad Q3-3(11.7mm,30.525mm) on Top Layer And Pad
Mahikhlun7 Soute All 45km on Ner Constraint: (0.202mm < 0.254mm) Between Pad Q3-3(11.7mm,30.525mm) on Top Layer And Pad
Mana (11.7mm,32.375mm) on Top Layer And Pad
Man են (Նահ այթ - Constraint: (0.047mm < 0.254mm) Between Pad Q3-4(11.7mm, 32.375mm) on Top Layer And Pad
Mani/hith75ondeβMasnoniver Constraint: (0.202mm < 0.254mm) Between Pad Q3-4(11.7mm,32.375mm) on Top Layer And Pad
Mana (Luh 7 Solde & Mask 1911) ver Constraint: (0.047mm < 0.254mm) Between Pad Q3-5(11.05mm, 32.375mm) on Top Layer And Pad
Mahiph(Lon4Sortda2Na3sknSh)ver Constraint: (0.187mm < 0.254mm) Between Pad Q3-7(10.75mm,31.45mm) on Top Layer And Pad
Mana (14-1/26.975mm, 30.695mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q4-2(27.625mm,30.695mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q4-3(28.275mm,30.695mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.202mm < 0.254mm) Between Pad Q4-3(28.275mm,30.695mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q4-4(28.275mm,32.545mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q4-4(28.275mm,32.545mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.202mm < 0.254mm) Between Pad Q4-4(28.275mm,32.545mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q4-5(27.625mm,32.545mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.187mm < 0.254mm) Between Pad Q4-7(27.325mm,31.62mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.198mm < 0.254mm) Between Pad Q5-1(41.115mm,66.966mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.198mm < 0.254mm) Between Pad Q5-1(41.115mm,67.916mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.198mm < 0.254mm) Between Pad Q5-4(38.385mm,68.866mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.198mm < 0.254mm) Between Pad Q5-4(36.385mm,67.916mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U1-1(30.325mm,11mm) on Top Layer And Pad U1-17(31.75mm,10.25mm, 10.25mm, 10.25mm, 11mm) on Top Layer And Pad U1-17(31.75mm, 10.25mm, 10.55mm, 10.25mm, 10.25m
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U1-1(30.325mm,11mm) on Top Layer And Pad U1-2(30.325mm,10.5mm)
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U1-10(33.175mm,10mm) on Top Layer And Pad
Minini (23.175mm, 10.015mm) on Top Layer And Pad
Minin Stroller Mask Binder Constraint: (0.047mm < 0.254mm) Between Pad U1-10(33.175mm,10mm) on Top Layer And Pad U1-9(33.175mm,9.5mm
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U1-11(33.175mm,10.5mm) on Top Layer And Pad
Minita(iiii). Stödern Mask is liver Constraint: (0.022mm < 0.254mm) Between Pad U1-11(33.175mm,10.5mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U1-12(33.175mm,11mm) on Top Layer And Pad
Minitri(2hi. Storoller, Maskrishner Constraint: (0.047mm < 0.254mm) Between Pad U1-13(32.5mm,11.675mm) on Top Layer And Pad
- U1-14(32mm,11.675mm)

Infinium Solder Mask Silver Constraint: (0.022mm < 0.254mm) Between Pad U1-13(32.5mm,11.675mm) on Top Layer And Pad Infinium Solder Mask Silver Constraint: (0.047mm < 0.254mm) Between Pad U1-14(32mm,11.675mm) on Top Layer And Pad Infinium Solder Mask Silver Constraint: (0.047mm < 0.254mm) Between Pad U1-14(32mm,11.675mm) on Top Layer And Pad Infinium Solder Mask Silver Constraint: (0.047mm < 0.254mm) Between Pad U1-15(31.5mm,11.675mm) on Top Layer And Pad Infinium Solder Mask Silver Constraint: (0.022mm < 0.254mm) Between Pad U1-15(31.5mm,11.675mm) on Top Layer And Pad Infinium Solder Mask Silver Constraint: (0.022mm < 0.254mm) Between Pad U1-16(31mm,11.675mm) on Top Layer And Pad Infinium Solder Mask Silver Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm,10.25mm) on Top Layer And Pad Infinium Solder Mask Silver Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm,10.25mm) on Top Layer And Pad U1-3(30.325mm,10mm) Infinium Solder Mask Silver Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm,10.25mm) on Top Layer And Pad U1-4(30.325mm,9.5mm) Infinium Solder Mask Silver Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm,10.25mm) on Top Layer And Pad U1-5(31mm,8.825mm) Infinium Solder Mask Silver Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm,10.25mm) on Top Layer And Pad U1-6(31.5mm,8.825mm) Infinium Solder Mask Silver Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm,10.25mm) on Top Layer And Pad U1-6(31.5mm,8.825mm) Infinium Solder Mask Silver Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm,10.25mm) on Top Layer And Pad U1-8(32.5mm,8.825mm) Infinium Solder Mask Silver Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm,10.25mm) on Top Layer And Pad U1-8(32.5mm,8.825mm) Infinium Solder Mask Silver Constraint: (0.047mm < 0.254mm) Between Pad U1-17(31.75mm,10.25mm) on Top Layer And Pad U1-8(32.5mm,8.825mm) on Top Layer And Pad U1-8(32.5mm,8.825mm) on Top Layer And Pad U1-8(33.5mm,8.825mm) on Top Layer And Pad U1-8(33.5mm,8.825mm) on Top Layer And Pa
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